



Notes:

- 1) Substrate size is 1/2" by 1/2" maximum. Overall thickness is less than .2". Backside is bare alumina. Unit will dissipate up to 2.5 Watts under some operating conditions. Provide adequate thermal path to heatsink for reliable operation.
- 2) External 10K thermistor is connected between Thermistor TP1 and TP2. This thermistor is used to sense TEC temperature . The hybrid substrate provides an output current to maintain the TEC (in cooling mode only) at a temperature which is set by an external TEC Rset resistor. Typical values of output current are in the 0 mA to 400 mA range.
- 3) External photodiode is connected between the Photodiode + and - inputs to monitor optical output of the laser. The output of the laser driver sources current to maintain this measured optical power at a level set by the Laser Rset resistor. Typical values of output current are in the 300 mA to 400 mA range.
- 4) Input enable pins for TEC and Laser pull to logic high. Apply ground or TTL logic Low to diable either or both outputs of the device.
- 5) Unit does not incorporate any PWM or other oscillating circuits.

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| Tolerances Except as Noted .x = +/- .05 .xx = +/- .01 .xxx = +/- .005 Dimensions in inches | Revisions | | | | <u>Impellimax</u> | | |
| | | | | | OUTLINE | | |
| | | | | | Not to Scale | | Sheet 1 of 1 |
| | | | | | Drawn By: PC | Date: 4/3/00 | Drawing # 4201-51 |
| Information herein is believed accurate. Suitability not guaranteed. | | | | DRF: 451 | Approved: PC | | |